

DMT3020LDV

# DUAL 30V N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8 (Type UXC)

#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C		
00)/	$20m\Omega$ @ $V_{GS} = 10V$	32A		
30V	$32m\Omega$ @ $V_{GS} = 4.5V$	25A		

#### **Features**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Description**

This new generation MOSFET is designed to minimize the on-state resistance ( $R_{DS(ON)}$ ), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

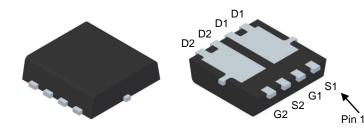
#### **Applications**

- Power Management Functions
- Analog Switch

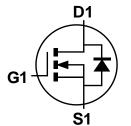
#### **Mechanical Data**

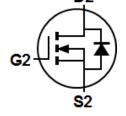
- Case: PowerDI<sup>®</sup>3333-8 (Type UXC)
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.072 grams (Approximate)

#### PowerDI3333-8 (Type UXC)









**Equivalent Circuit** 

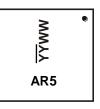
### **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMT3020LDV-7	PowerDI3333-8 (Type UXC)	2,000/Tape & Reel
DMT3020LDV-13	PowerDI3333-8 (Type UXC)	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## Marking Information



AR5 = Product Type Marking Code

YYWW = Date Code Marking

YY = Last Two Digits of Year (ex: 18 for 2018)

WW = Week Code (01 to 53)



#### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			$V_{GSS}$	±20	V
Continuous Drain Current, $V_{GS} = 10V$ (Note 7) Steady $T_{C} = +25^{\circ}C$ State $T_{C} = +70^{\circ}C$			I <sub>D</sub>	32 25	А
Maximum Body Diode Forward Current (Note 7)			Is	25	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I <sub>DM</sub>	50	Α
Pulsed Drain Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)			I <sub>SM</sub>	50	Α
Avalanche Current (L = 0.1mH) (Note 8)			I <sub>AS</sub>	13	Α
Avalanche Energy (L = 0.1mH) (Note 8)			E <sub>AS</sub>	8.5	mJ

# Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		$P_{D}$	0.9	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	138	°C/W
Total Power Dissipation (Note 6)		P <sub>D</sub>	1.9	W
Thermal Resistance, Junction to Ambient (Note 6)  Steady State		$R_{ heta JA}$	67	°C/W
Thermal Resistance, Junction to Case (Note 7)	$R_{ heta JC}$	4.8	C/VV	
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +150	°C

## Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30.0	l	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C		_		1.0	μΑ	$V_{DS} = 24V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1.0		2.5	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance			14	20	mΩ	$V_{GS} = 10V, I_D = 9.0A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	_	22	32		$V_{GS} = 4.5V, I_D = 7.0A$	
Diode Forward Voltage	$V_{SD}$	_	8.0	1.2	V	$V_{GS} = 0V$ , $I_S = 2A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C <sub>iss</sub>		393	_	рF	15 15 16 16 16 16 16 16 16 16 16 16 16 16 16	
Output Capacitance	Coss	_	173	_	рF	$V_{DS} = 15V, V_{GS} = 0V,$ - f = 1.0MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	27	_	pF	-1 = 1.0lvinz	
Gate Resistance	$R_{g}$	_	1.1	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MH$	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	7.0	_	nC		
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_{g}$	_	3.6	_	nC	15)/ 1 00	
Gate-Source Charge	Q <sub>gs</sub>	_	0.9	_	nC	$V_{DD} = 15V, I_D = 9A$	
Gate-Drain Charge	$Q_{gd}$	_	1.5	_	nC	1	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	1.8	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	1.9	_	ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V,	
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	7.5	_	ns	$R_G = 6\Omega$ , $I_D = 9A$	
Turn-Off Fall Time	t <sub>F</sub>	_	2.4	_	ns		
Reverse Recovery Time	t <sub>RR</sub>	_	10	_	ns	1 04 11/14 1004/	
Reverse Recovery Charge	Q <sub>RR</sub>	_	2.6	_	nC	$I_F = 9A$ , $dI/dt = 100A/\mu s$	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

<sup>6.</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
7. Thermal resistance from junction to soldering point (on the exposed drain pad).

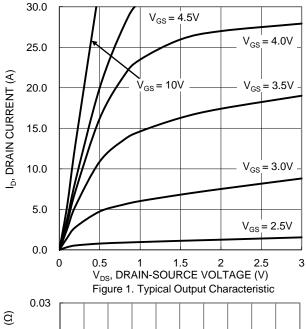
<sup>8.</sup>  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J = +25$ °C.

<sup>9.</sup> Short duration pulse test used to minimize self-heating effect.

<sup>10.</sup> Guaranteed by design. Not subject to product testing.







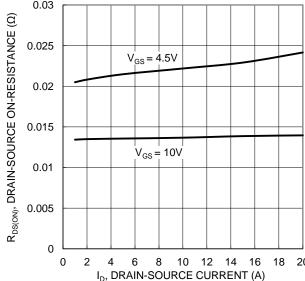


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

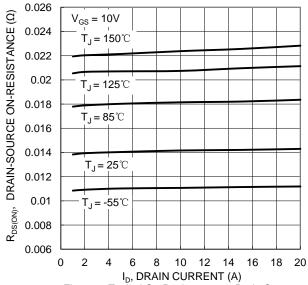
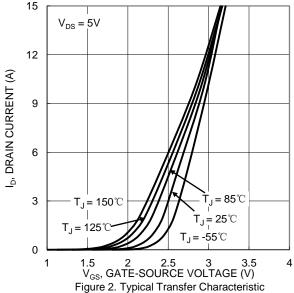
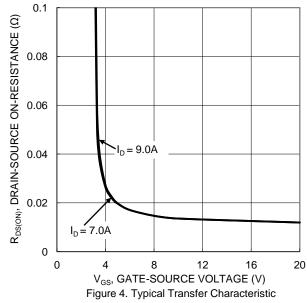


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature





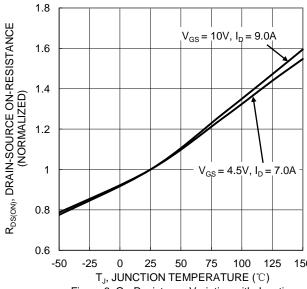


Figure 6. On-Resistance Variation with Junction Temperature





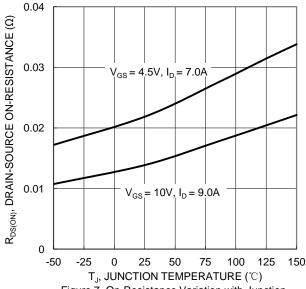
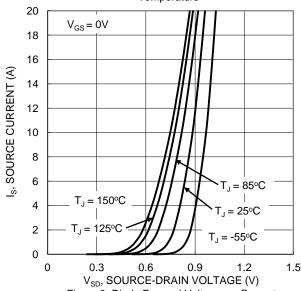


Figure 7. On-Resistance Variation with Junction Temperature



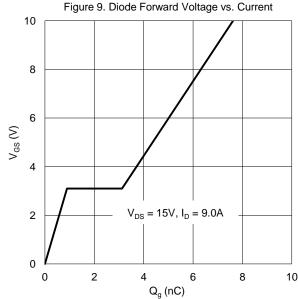
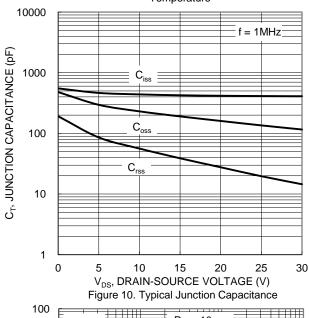
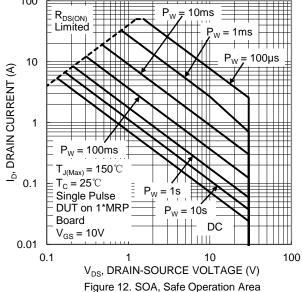


Figure 11. Gate Charge

2  $V_{GS(TH)},$  GATE THRESHOLD VOLTAGE (V) 1.8  $I_D = 1 \text{mA}$ 1.6 1.4 I<sub>D</sub>= 250μA 1.2 1 8.0 0.6 50 -50 -25 25 75 100 125 150 T<sub>.i</sub>, JUNCTION TEMPERATURE (°C)

Figure 8. Gate Threshold Variation vs. Junction Temperature







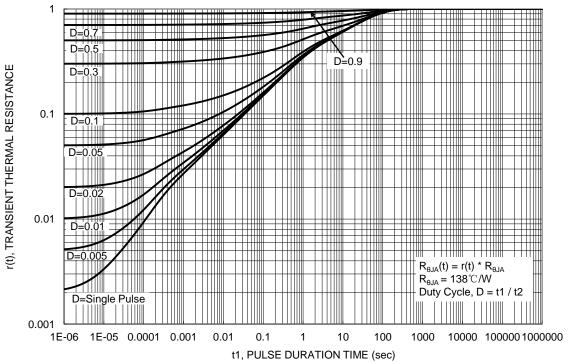


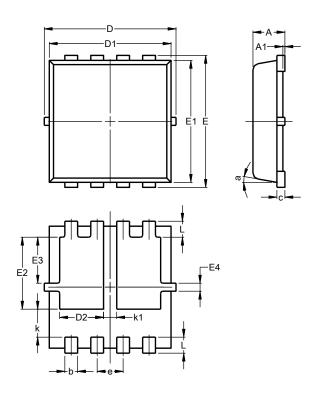
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (Type UXC)

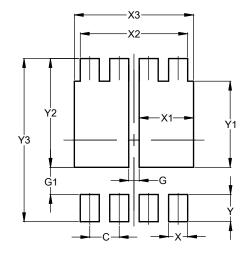


PowerDI3333-8					
(Type UXC)					
Dim	Min Max Typ				
Α	0.75	0.85	0.80		
<b>A</b> 1	0.00	0.05			
b	0.25	0.40	0.32		
С	0.10	0.25	0.15		
D	3.20	3.40	3.30		
D1	2.95	3.15	3.05		
D2	0.90	1.30	1.10		
Е	3.20	3.40	3.30		
E1	2.95	3.15	3.05		
E2	1.60	2.00	1.80		
E3	0.95	1.35	1.15		
E4	0.10	0.30	0.20		
е	-	-	0.65		
L	0.30	0.50	0.40		
k	0.50	0.90	0.70		
k1	0.13	0.53	0.33		
а	0°	12°	10°		
All Dimensions in mm					

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (Type UXC)



Dimensions	Value (in mm)		
С	0.650		
G	0.230		
G1	0.600		
Х	0.420		
X1	1.200		
X2	2.370		
Х3	2.630		
Y	0.600		
Y1	1.900		
Y2	2.400		
Y3	3.600		

May 2018 © Diodes Incorporated



#### **IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### **LIFE SUPPORT**

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2018, Diodes Incorporated

www.diodes.com